



(0,50 mm) .0197"

BTH SERIES

BASIC BLADE & BEAM HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTH

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2.0 A per pin (1 pin powered per row)
Flammability Rating: UL 94 V0
Operating Temp Range: -55°C to +125°C
Voltage Rating: 275 VAC
Max Cycles: 100
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity:
 Vertical= (0,10 mm) .004" max (030-090)
 Vertical= (0,15 mm) .006" max (120-150)
 Right Angle= (0,15 mm) .006" max (030-090)
Board Stacking:
 For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Edge Mount Capability
 - 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTH - **NO. OF POSITIONS PER ROW** - **01** - **PLATING OPTION** - **D** - **A** - **OTHER OPTION**

Mates with: BSH

-030, -050, -060, -090, -120, -150

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K
= (7,00 mm) .276" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (120 positions maximum)

*Note: -C Plating passes 10 year MFG testing



BTH - **NO. OF POSITIONS PER ROW** - **01** - **PLATING OPTION** - **D** - **RA** - **WT** - **OTHER OPTION**

Mates with: BSH

-030, -060, -090

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-K
= (7,00 mm) .276" DIA Polyimide Film Pick & Place Pad

Due to technical progress, all designs, specifications and components are subject to change without notice.

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